



ZHCS1000

#### SURFACE MOUNT SCHOTTKY BARRIER DIODE

# **Product Summary**

| V <sub>RRM</sub> (V) | I <sub>O</sub> (A) | V <sub>F(TYP)</sub> @ 1A<br>(V) | I <sub>R(TYP)</sub> @ V <sub>R</sub> =30V<br>(μA) |
|----------------------|--------------------|---------------------------------|---|
| 40                   | 1                  | 0.425                           | 50  |

#### **Features and Benefits**

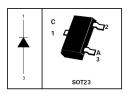
- High current capability (I<sub>F</sub> = 1A)
- Low V<sub>F</sub>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Description and Applications**

- DC DC Converters
- Mobile Telecomms
- PCMIA & SCSI

### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe.
  Solderable per MIL-STD-202, Method 208 <sup>®3</sup>
- Weight: 0.0089 grams (approximate)



Top View

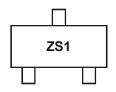
### **Ordering Information** (Note 4)

| Device     | Packaging | Shipping         |
|------------|-----------|------------------|
| ZHCS1000TA | SOT23     | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



ZS1 = Product Type Marking Code



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Character                                   | Symbol           | Value            | Units |   |
|---|------------------|------------------|-------|---|
| Continuous Reverse Voltage                  |                  | $V_R$            | 40    | V |
| Continuous Forward Current                  |                  | l <sub>F</sub>   | 1     | Α |
| Forward Voltage @ I <sub>F</sub> = 1A (typ) | V <sub>F</sub>   | 425              | mV    |   |
| Average Peak Forward Current; D.C. = 50     | I <sub>FAV</sub> | 1750             | mA    |   |
| Non Repetitive Forward Current              | t ≤ 100µs        | I <sub>FSM</sub> | 12    | Α |
| Non Repetitive Forward Current              | t ≤ 10ms         |                  | 5.2   | Α |

## **Thermal Characteristics**

| Characteristic                            | Symbol           | Value       | Unit |
|---|------------------|-------------|------|
| Power Dissipation, T <sub>A</sub> = +25°C | $P_{D}$          | 500         | mW   |
| Junction Temperature                      | TJ               | +125        | °C   |
| Storage Temperature Range                 | T <sub>STG</sub> | -55 to +150 | °C   |

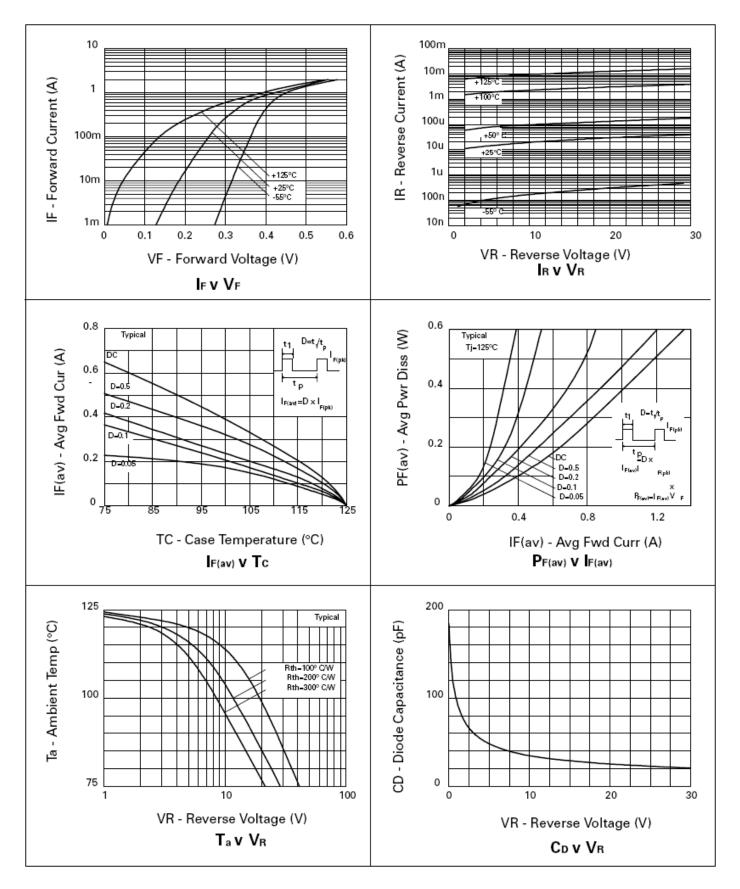
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic            | Symbol             | Min | Тур | Max | Unit | Test Condition   |
|---------------------------|--------------------|-----|-----|-----|------|--|
| Reverse Breakdown Voltage | V <sub>(BR)R</sub> | 40  | 60  | _   | V    | I <sub>R</sub> = 300μA   |
|                           | VF                 | _   | 240 | 270 |      | I <sub>F</sub> = 50mA  |
|                           |                    | _   | 265 | 290 | mV   | I <sub>F</sub> = 100mA   |
|                           |                    | _   | 305 | 340 |      | I <sub>F</sub> = 250mA   |
| Forward Voltage (Note 5)  |                    | _   | 355 | 400 |      | I <sub>F</sub> = 500mA   |
| Forward Voltage (Note 5)  |                    | _   | 390 | 450 |      | I <sub>F</sub> = 750mA   |
|                           |                    | _   | 425 | 500 |      | I <sub>F</sub> = 1A  |
|                           |                    | _   | 495 | 600 |      | I <sub>F</sub> = 1.5A  |
|                           |                    | _   | 420 | _   |      | I <sub>F</sub> = 1A, T <sub>A</sub> = +100°C                         |
| Reverse Current (Note 6)  | I <sub>R</sub>     | _   | 50  | 100 | μA   | V <sub>R</sub> = 30V   |
| Total Capacitance         | Ст                 | _   | 25  | _   | pF   | f = 1MHz, V <sub>R</sub> = 30V                                       |
| Reverse Recovery Time     | trr                | _   | 12  | _   | ns   | Switched from $I_F$ = 500mA to $I_R$ = 500mA Measured @ $I_R$ = 50mA |

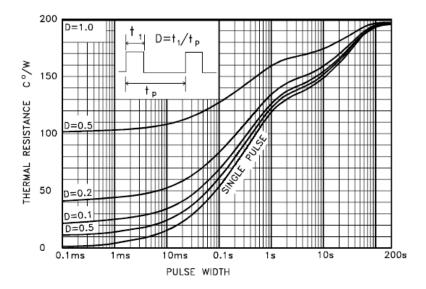
Notes:

- 5. Measured under pulsed conditions. Pulse width =  $300\mu S$ . 6. Short duration pulse test used to minimize self-heating effect.





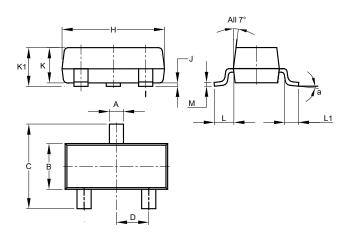




MAXIMUM TRANSIENT THERMAL RESISTANCE\*

# **Package Outline Dimensions**

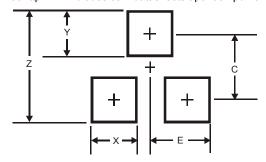
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SOT23                |       |       |       |  |  |
|----------------------|-------|-------|-------|--|--|
| Dim                  | Min   | Max   | Тур   |  |  |
| Α                    | 0.37  | 0.51  | 0.40  |  |  |
| В                    | 1.20  | 1.40  | 1.30  |  |  |
| С                    | 2.30  | 2.50  | 2.40  |  |  |
| D                    | 0.89  | 1.03  | 0.915 |  |  |
| F                    | 0.45  | 0.60  | 0.535 |  |  |
| G                    | 1.78  | 2.05  | 1.83  |  |  |
| Н                    | 2.80  | 3.00  | 2.90  |  |  |
| J                    | 0.013 | 0.10  | 0.05  |  |  |
| K                    | 0.890 | 1.00  | 0.975 |  |  |
| K1                   | 0.903 | 1.10  | 1.025 |  |  |
| L                    | 0.45  | 0.61  | 0.55  |  |  |
| L1                   | 0.25  | 0.55  | 0.40  |  |  |
| M                    | 0.085 | 0.150 | 0.110 |  |  |
| а                    | a 8°  |       |       |  |  |
| All Dimensions in mm |       |       |       |  |  |

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |  |  |
|------------|---------------|--|--|
| Z          | 2.9           |  |  |
| Х          | 0.8           |  |  |
| Υ          | 0.9           |  |  |
| С          | 2.0           |  |  |
| E          | 1.35          |  |  |

<sup>\*</sup> Devices were mounted on a 15mmx15mm ceramic substrate.



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